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(54) POSITIVE AND NEGATIVE VOLTAGE LEVEL SHIFTER CIRCUIT

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Related U.S. Application Data

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- (60) Provisional application No. 60/980,017, filed on Oct. 15, 2007.
- (51) Int. Cl. G11C 7/00 (2006.01)
- (52) **U.S. Cl.** **365/189.11**; 365/189.12; 365/189.07

See application file for complete search history.

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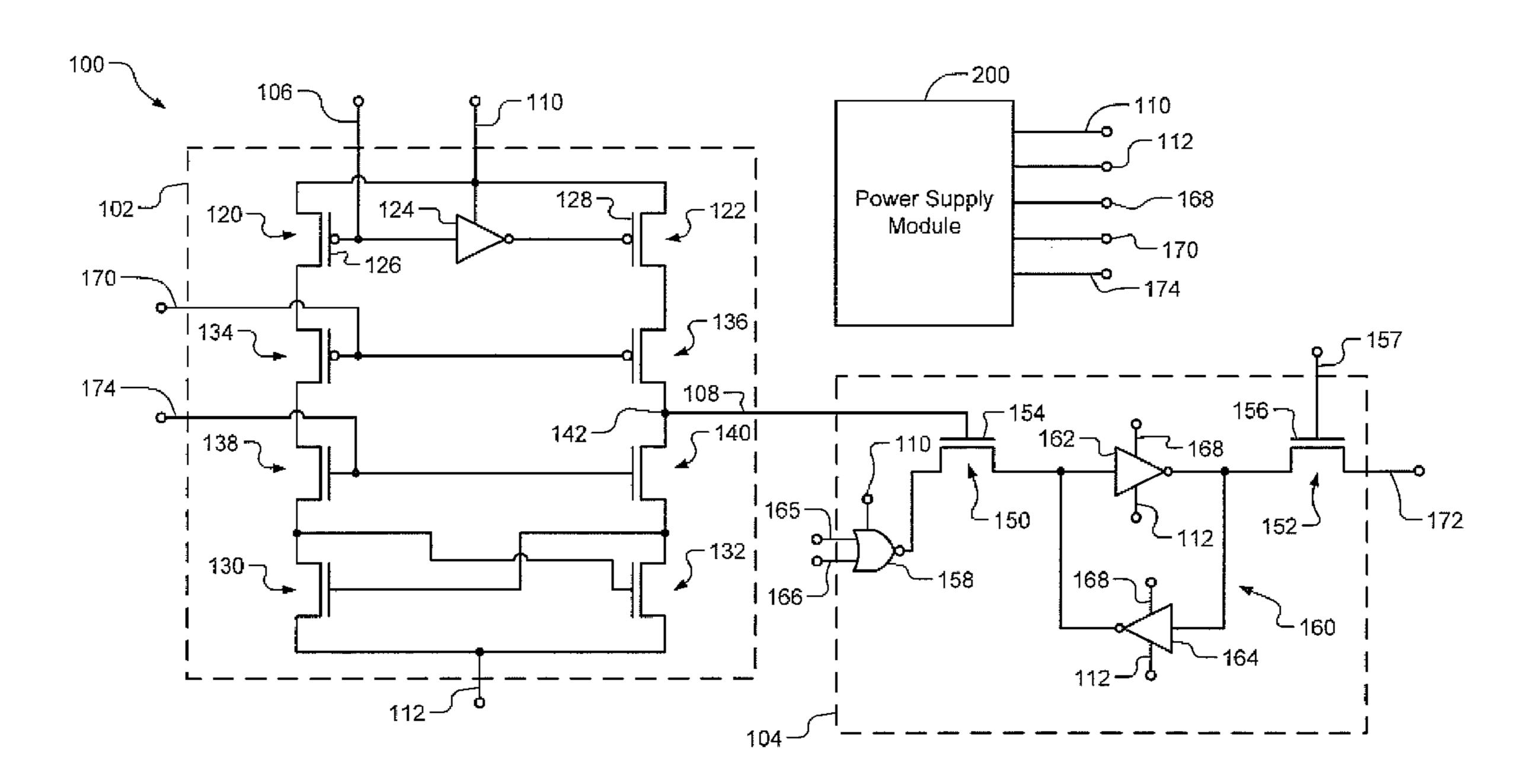
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Primary Examiner — Dang Nguyen

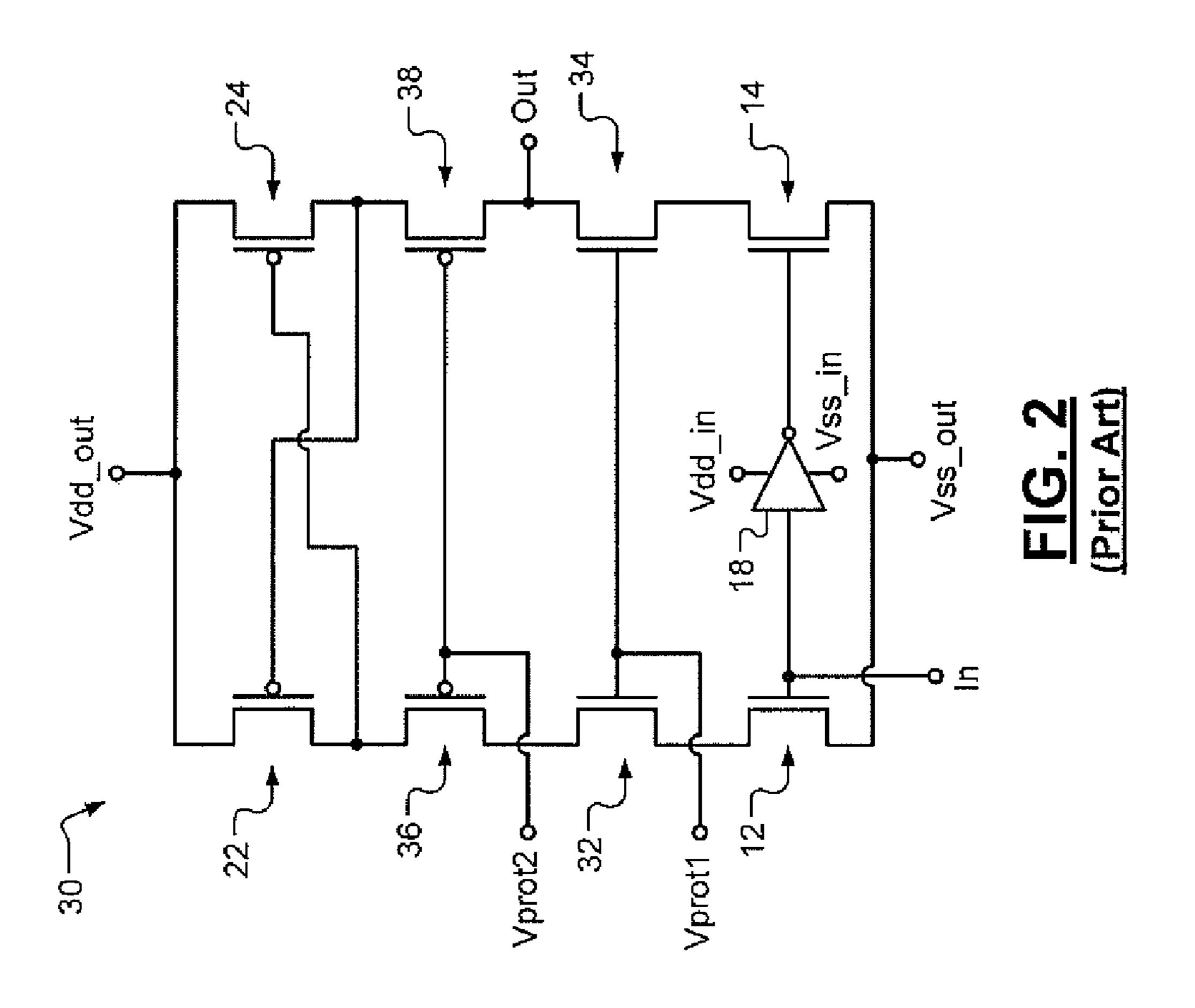
(57) ABSTRACT

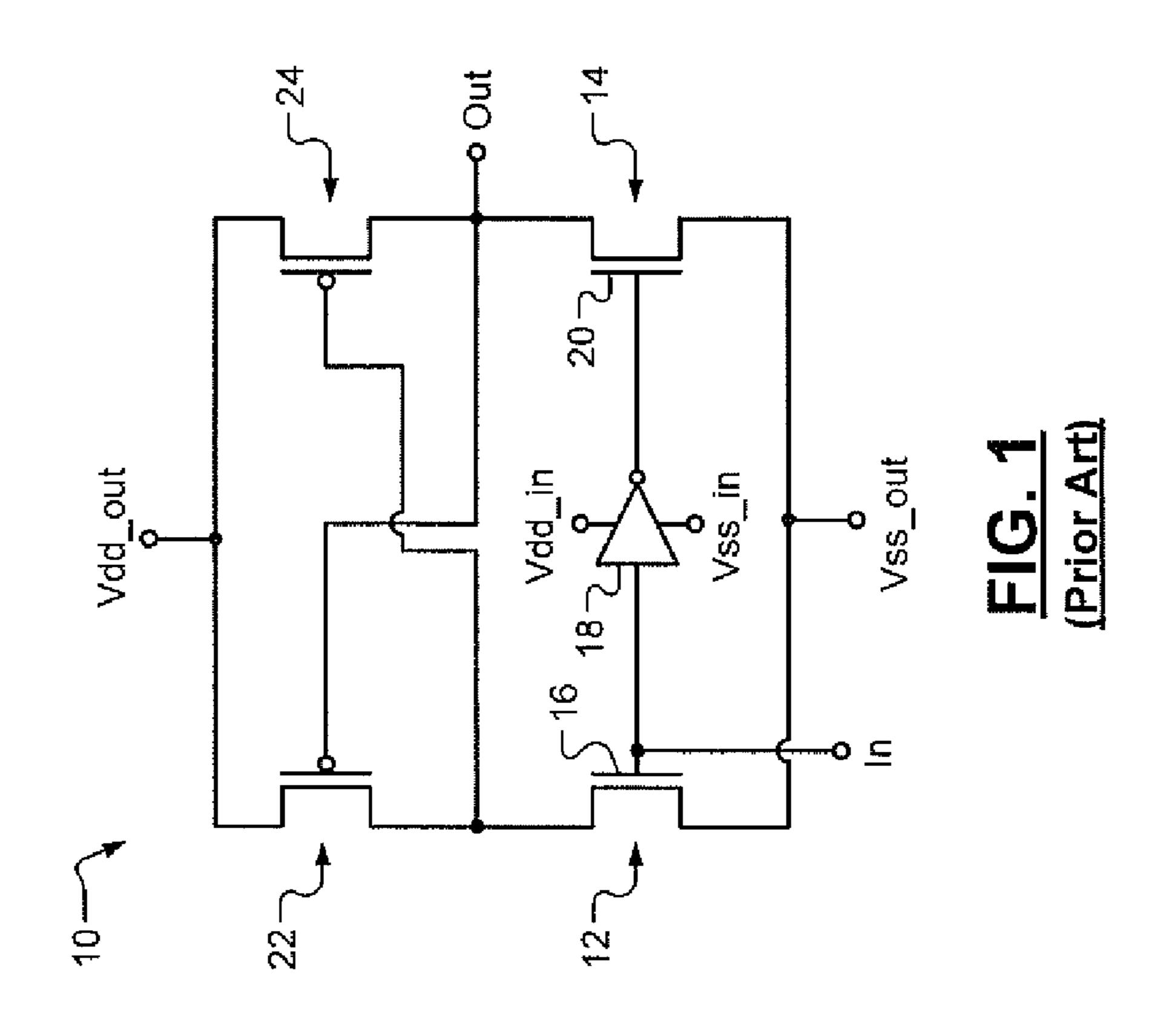
A level shifter including a level shifter module configured to i) receive an input signal, wherein the input signal varies between a first level and a second level, ii) receive a first voltage supply signal and a second voltage supply signal, and iii) generate a latch control signal based on the input signal and one of the first voltage supply signal and the second voltage supply signal. The level shifter further includes a latch module configured to i) receive the latch control signal, ii) receive the second voltage supply signal and a third voltage supply signal, and iii) generate an output signal based on the latch control signal and one of the second voltage supply signal and the third voltage supply signal.

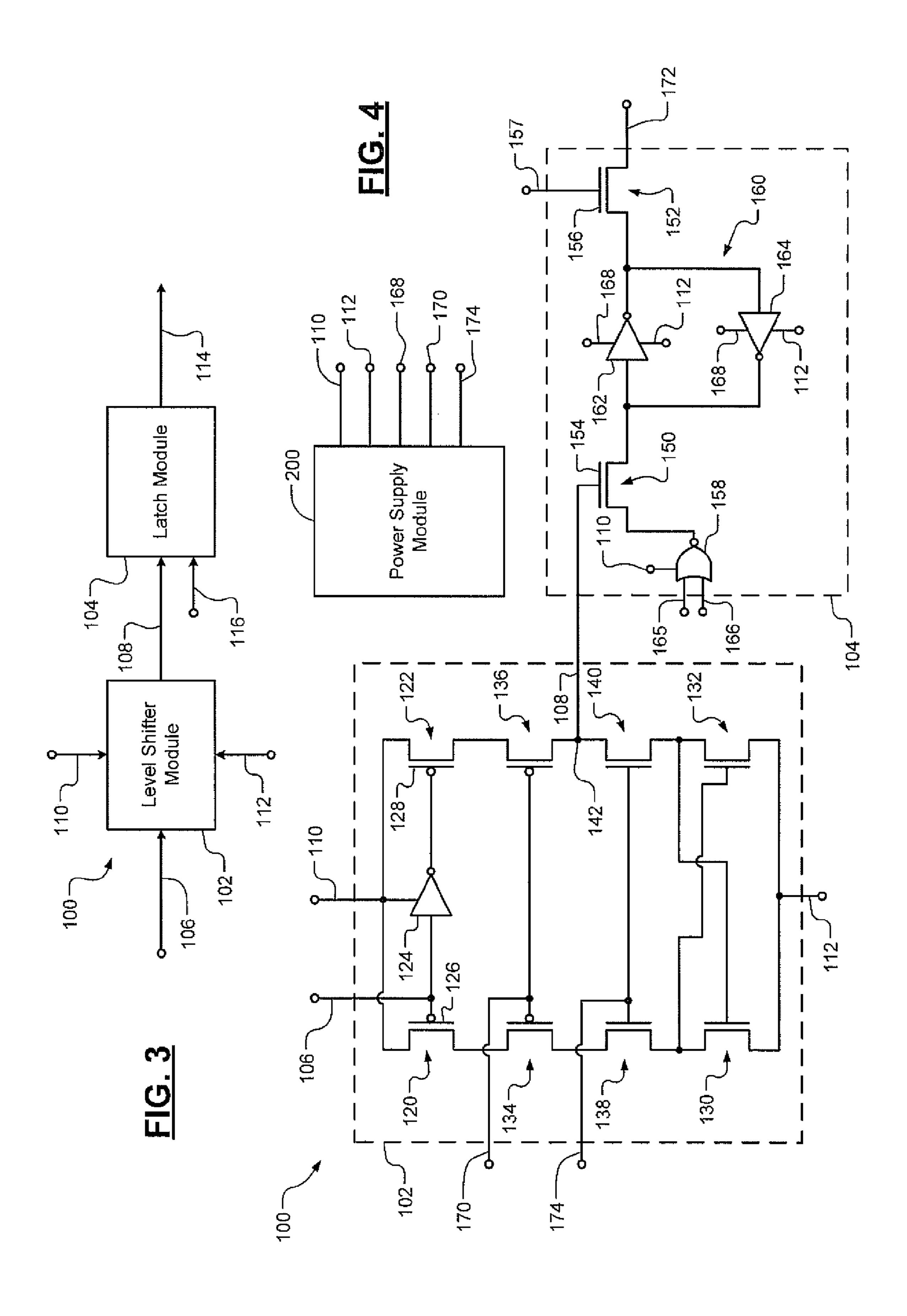
16 Claims, 12 Drawing Sheets

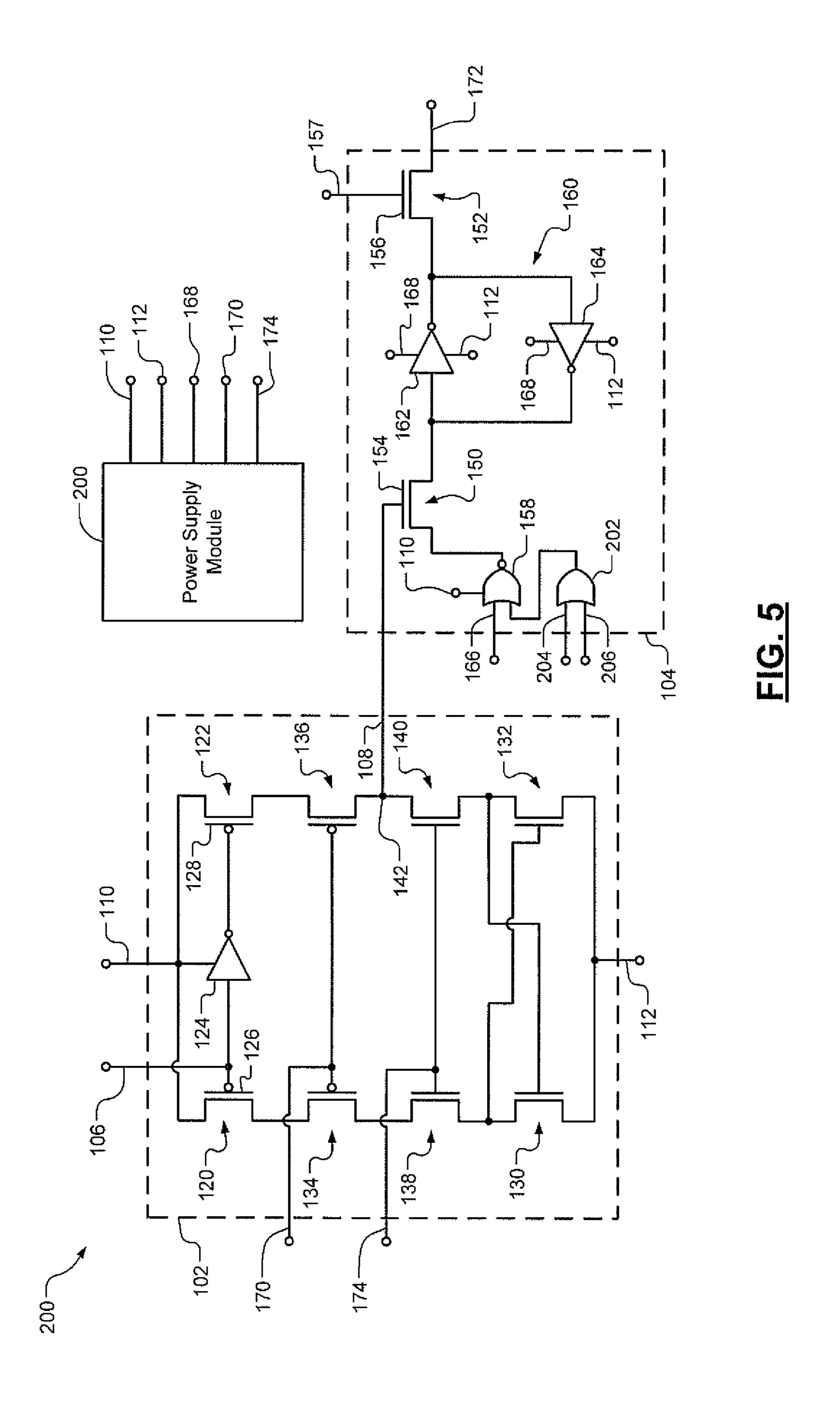


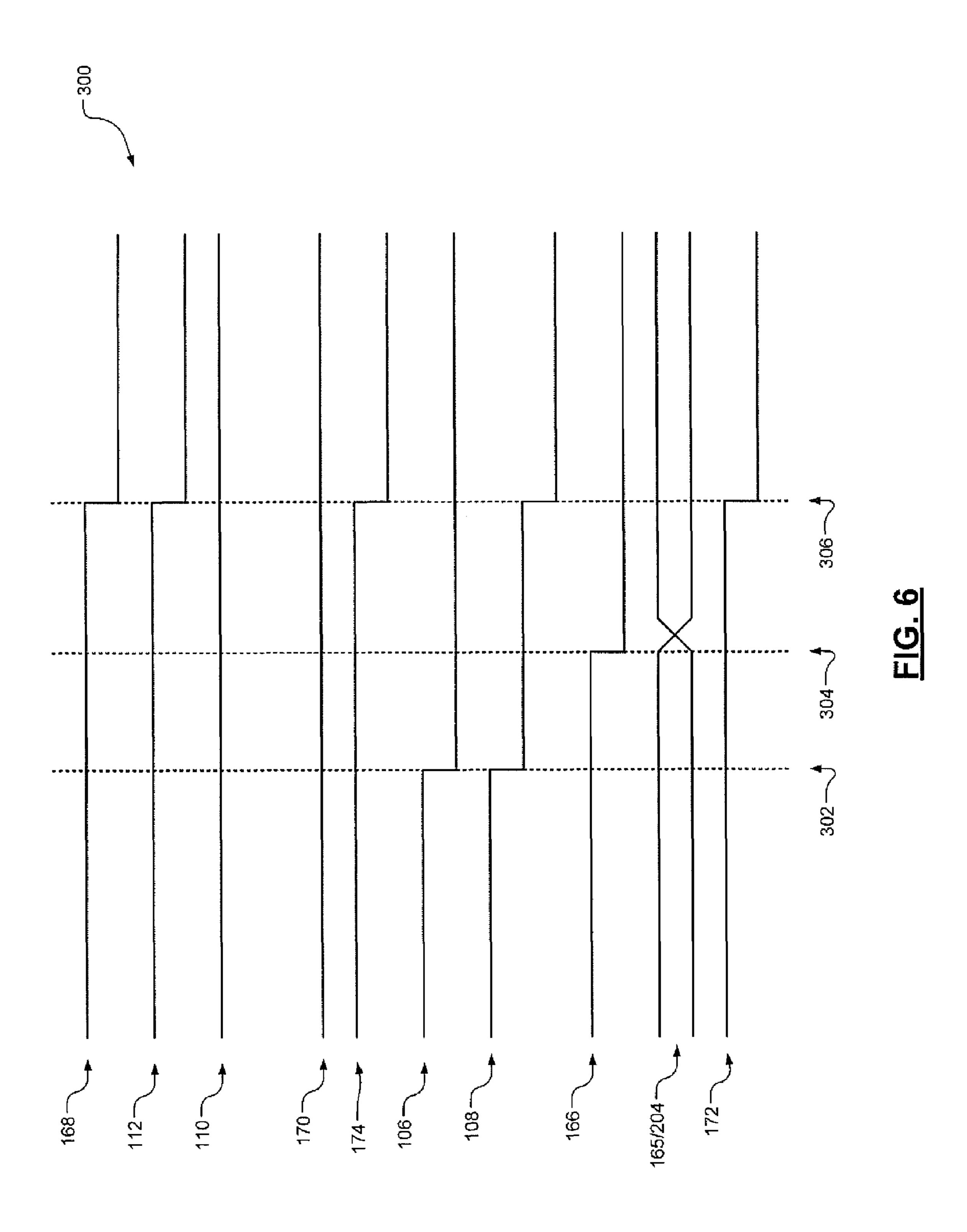
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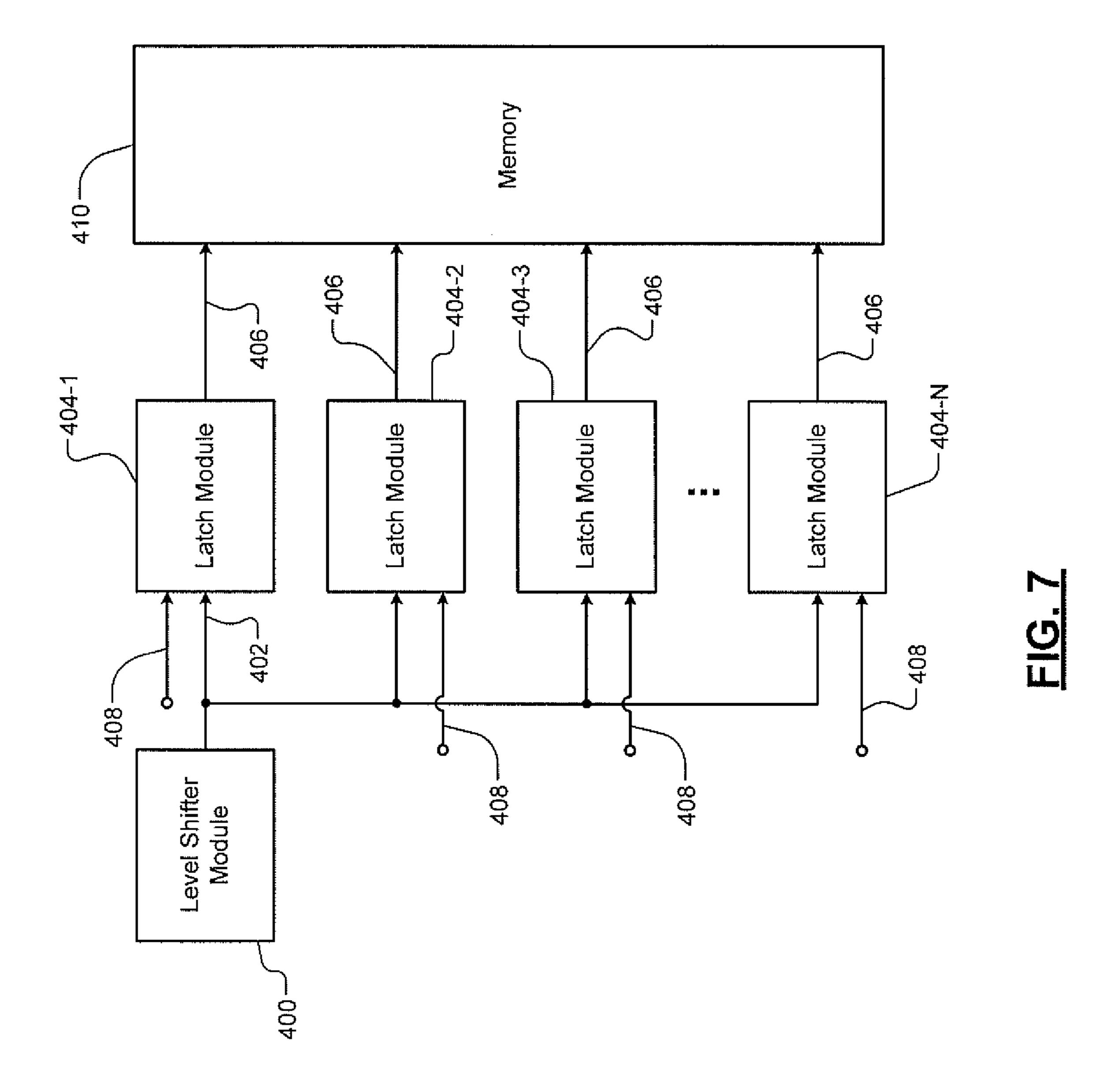












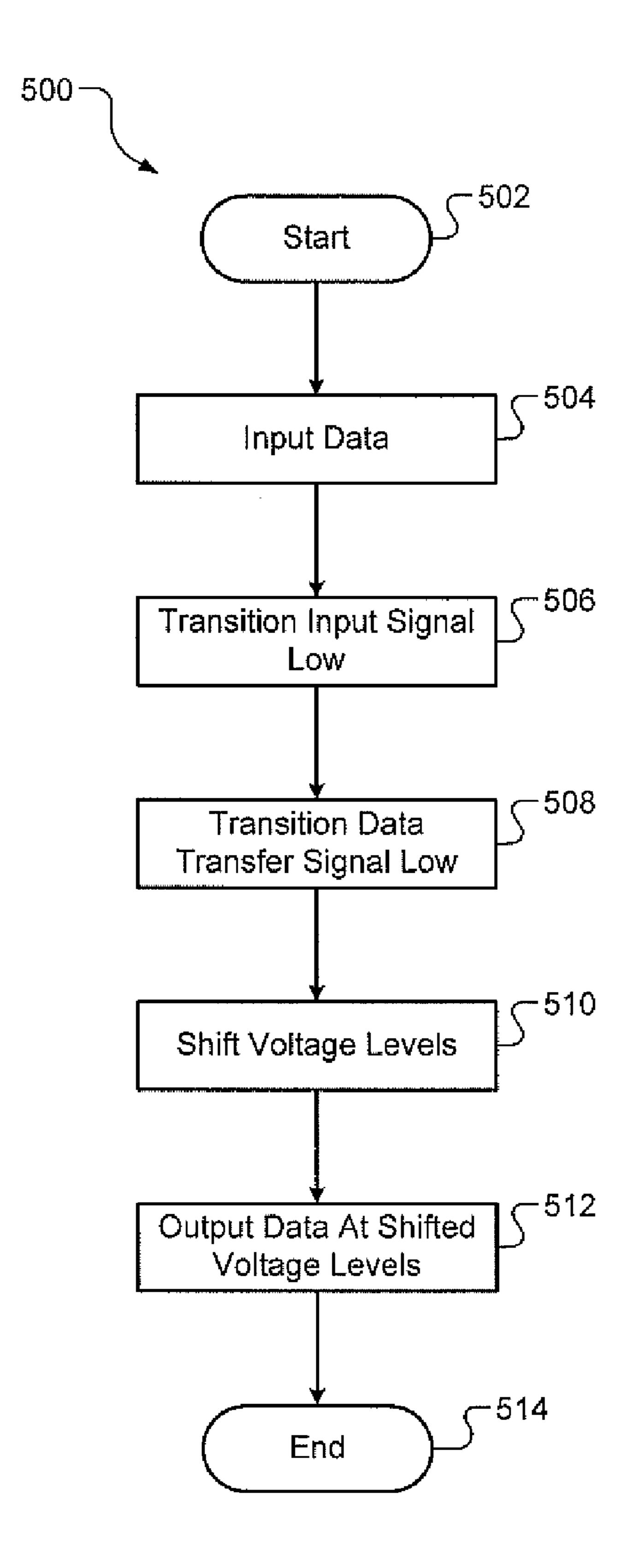


FIG. 8

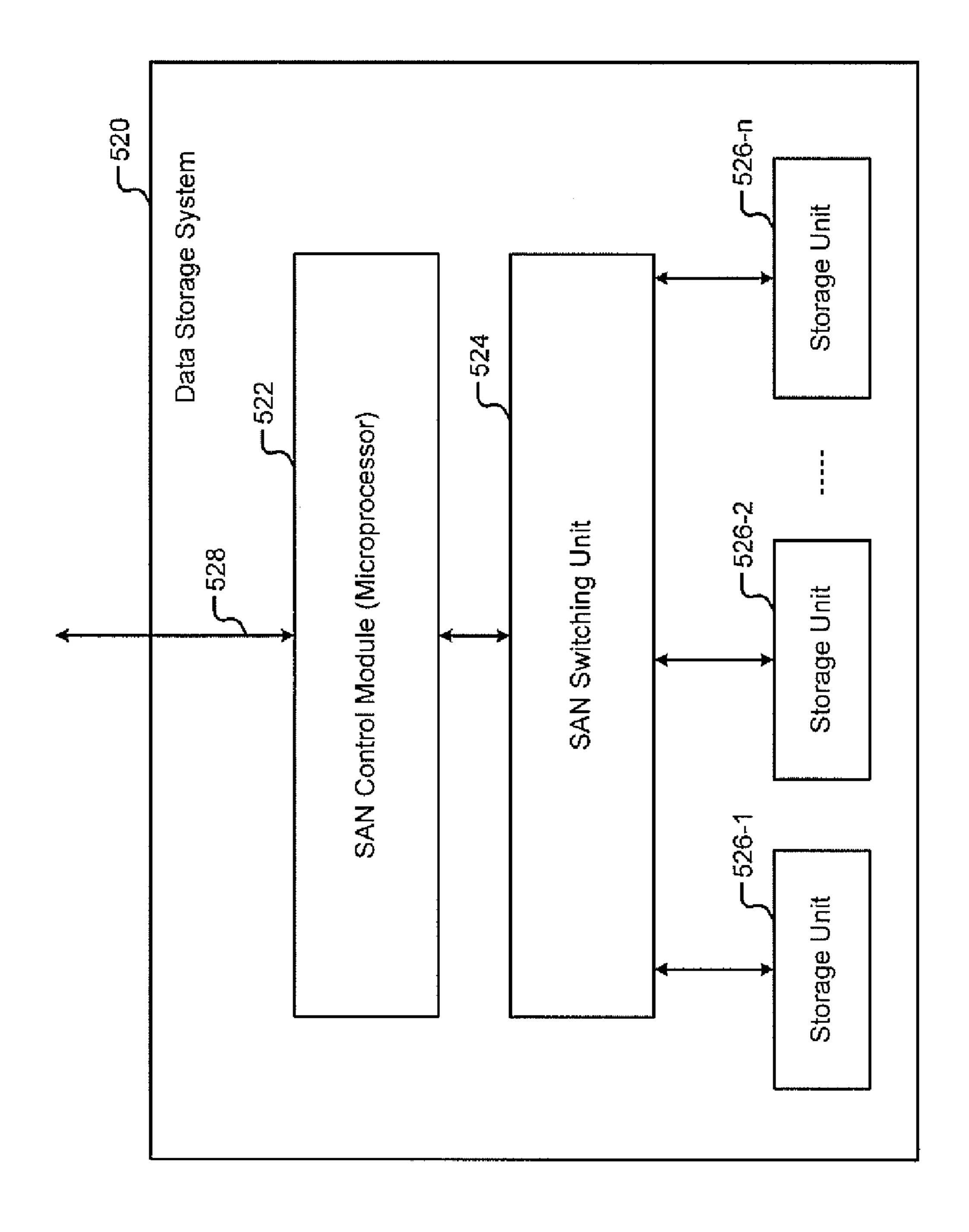
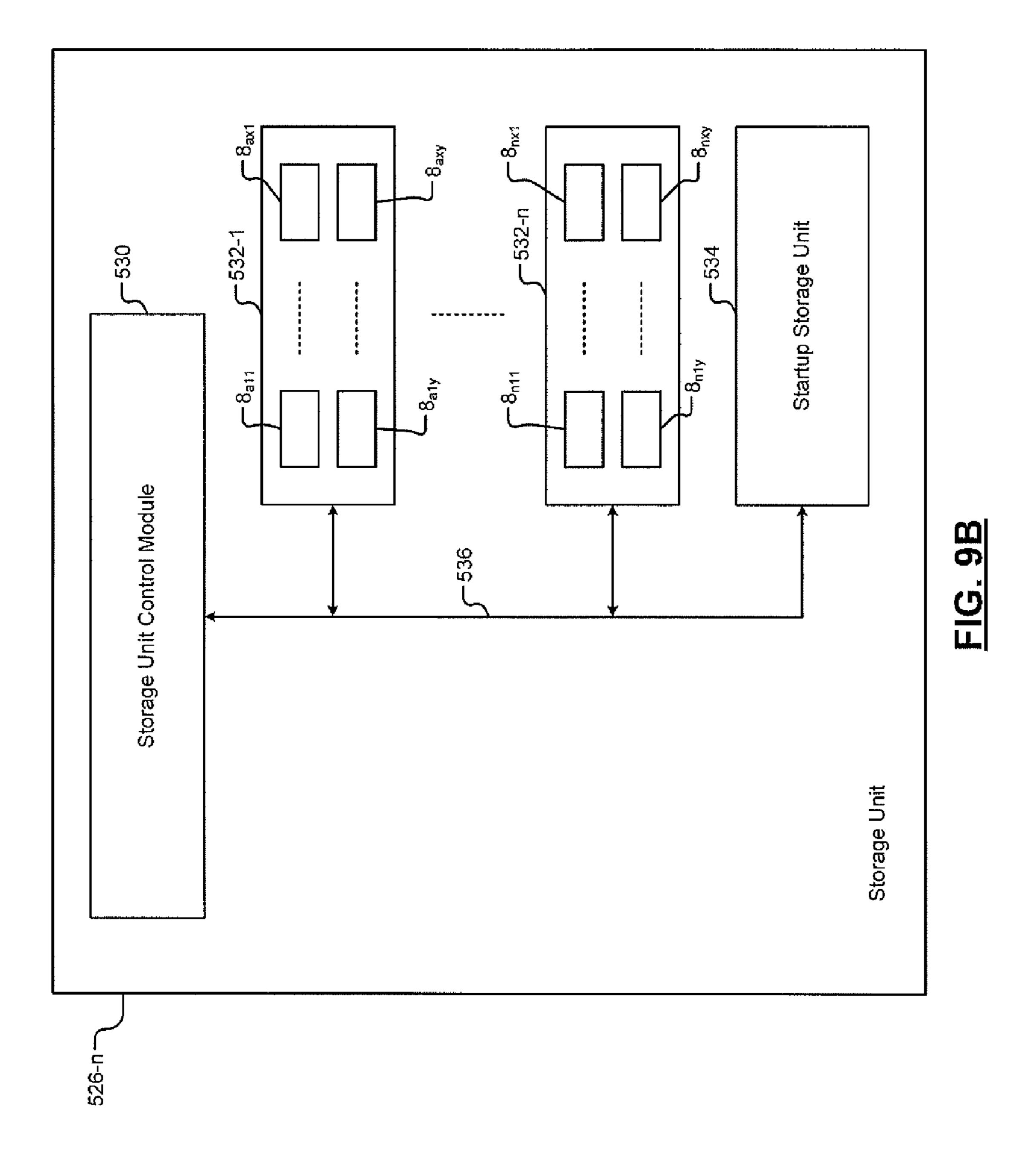


FIG. 9A



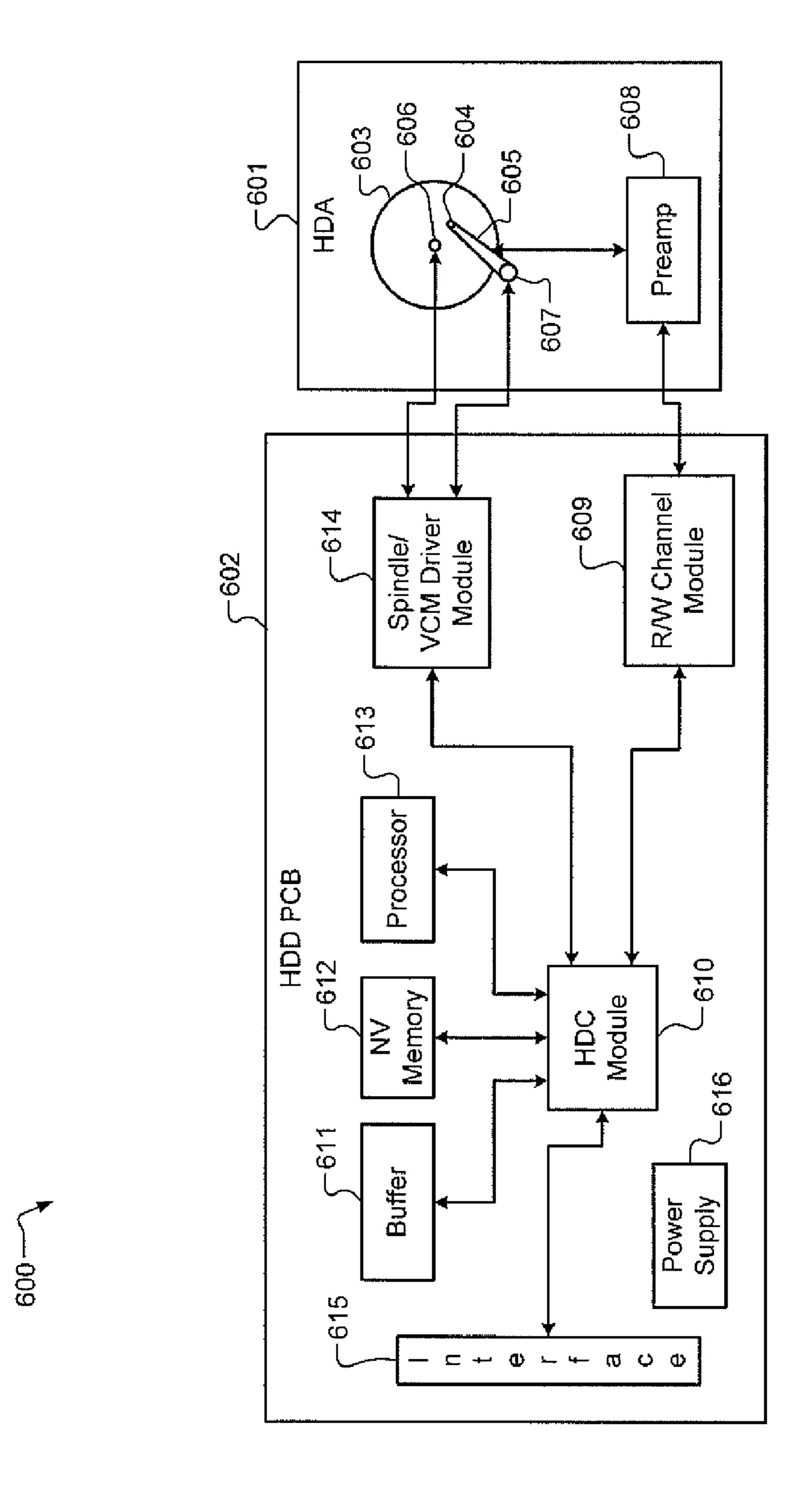


FIG. 90

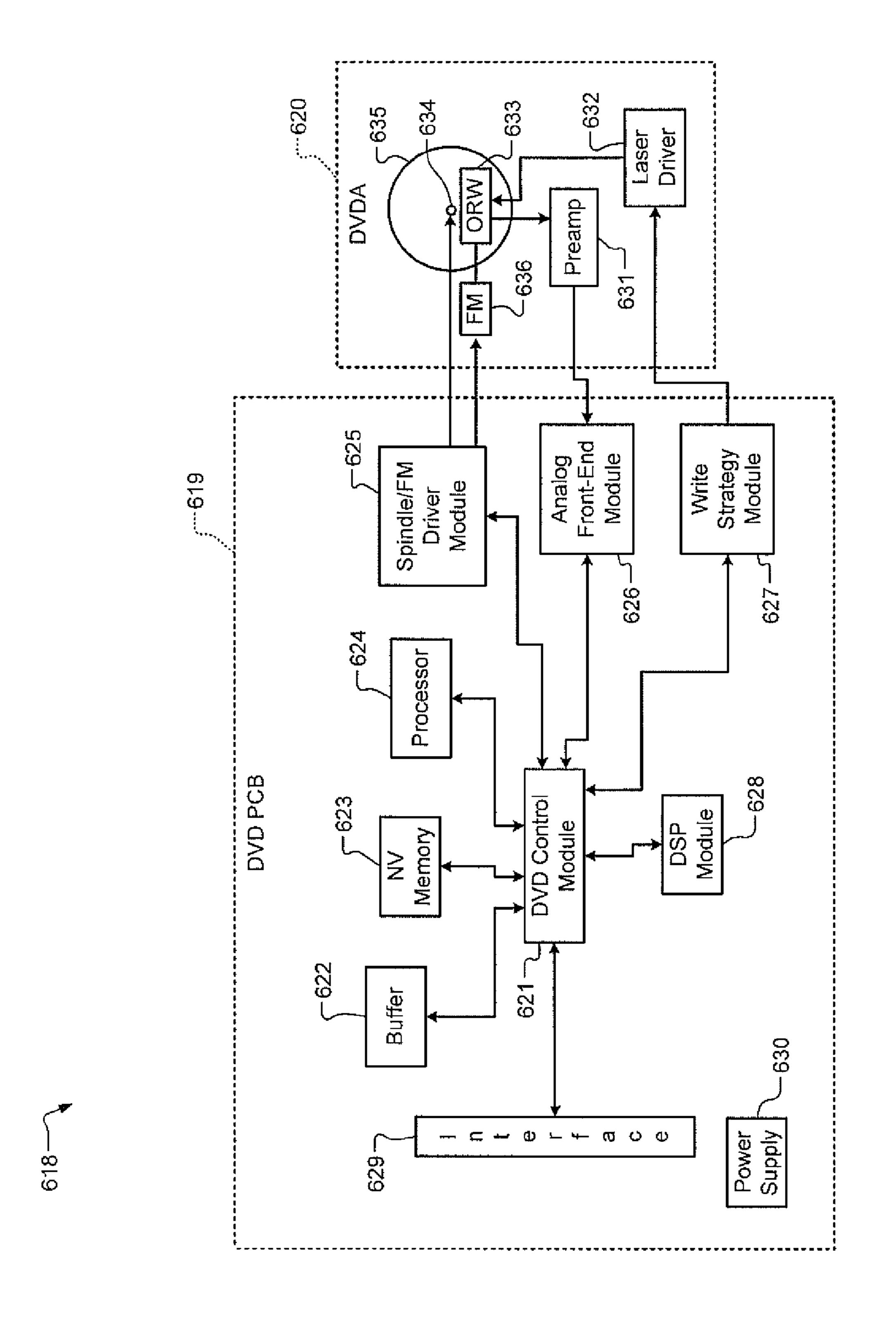
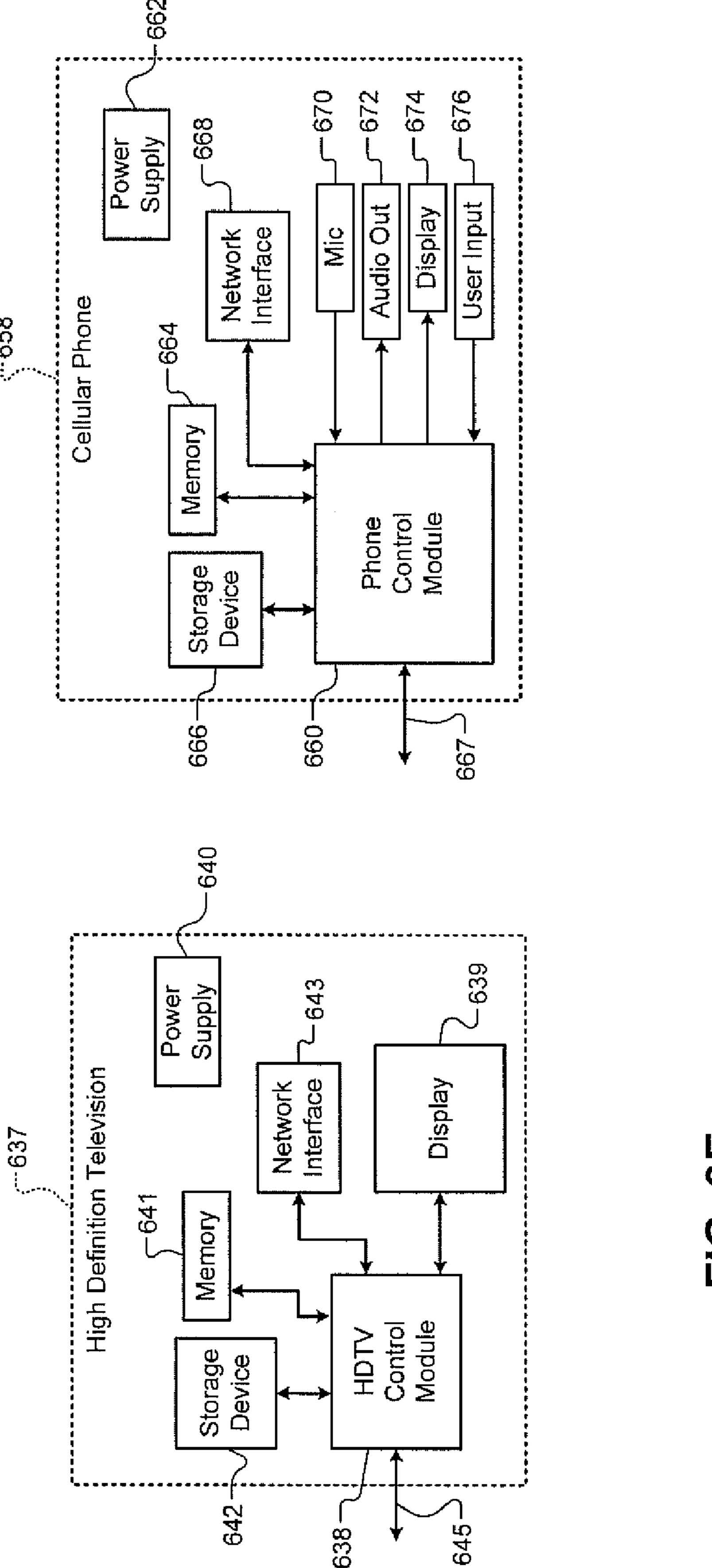
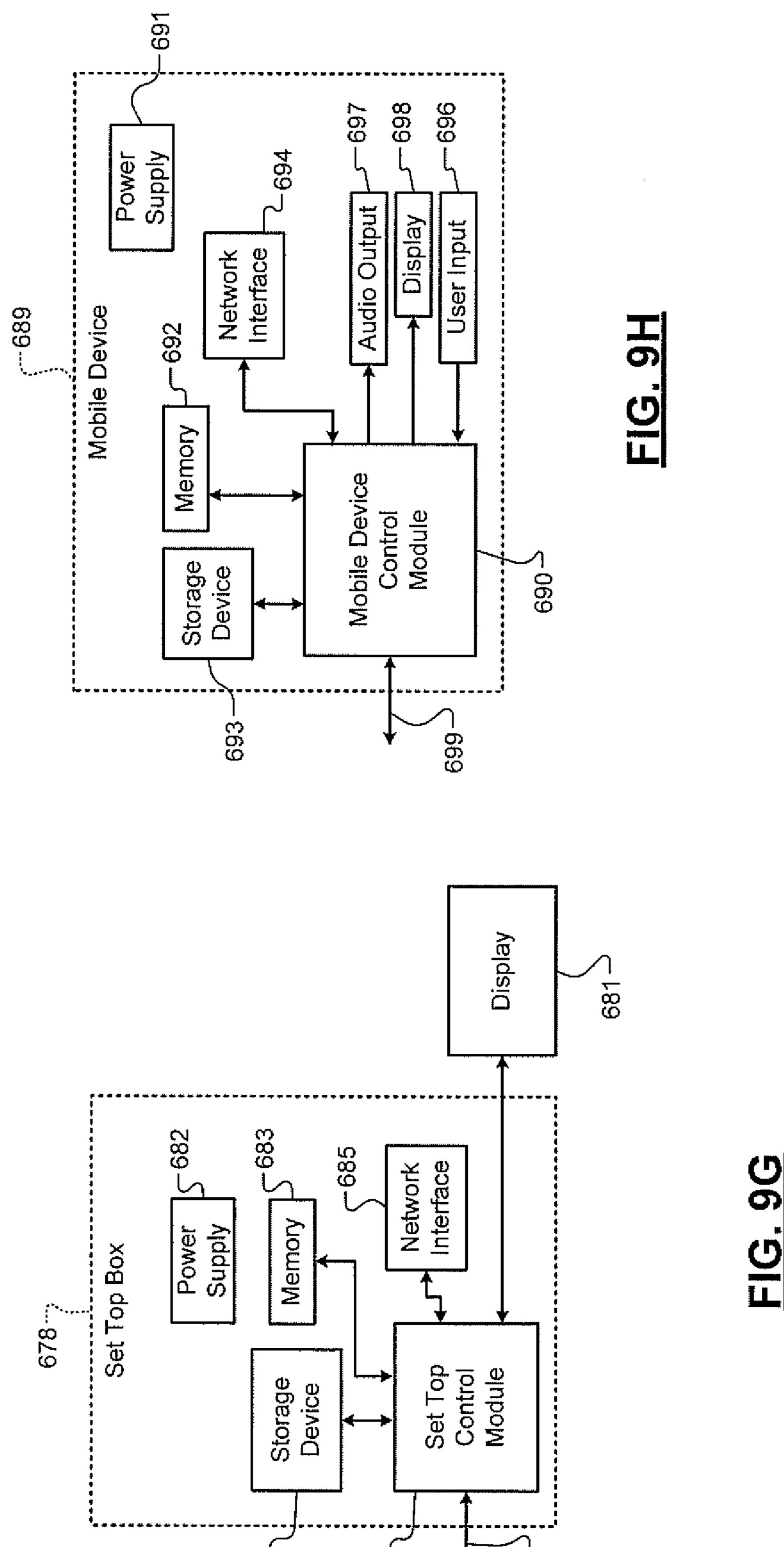


FIG. 9D

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POSITIVE AND NEGATIVE VOLTAGE LEVEL SHIFTER CIRCUIT

CROSS-REFERENCE TO RELATED APPLICATIONS

This present disclosure is a continuation of U.S. application Ser. No. 12/250,021 (now U.S. Pat. No. 7,948,810), filed on Oct. 13, 2008, which claims priority under 35 U.S.C. §119(e) to U.S. Provisional Application No. 60/980,017, filed on Oct. 15, 2007.

FIELD

The present disclosure relates to level shifters, and more particularly to a level shifter having a greater output voltage range.

BACKGROUND

The background description provided herein is for the purpose of generally presenting the context of the disclosure. Work of the presently named inventors, to the extent the work is described in this background section, as well as aspects of the description that may not otherwise qualify as prior art at 25 the time of filing, are neither expressly nor impliedly admitted as prior art against the present disclosure.

Referring now to FIG. 1, a level shifter 10 is shown. The level shifter 10 receives an input voltage Vin and generates an output voltage Vout. The level shifter 10 may include first and 30 second NMOS transistors 12 and 14. A gate 16 of the first NMOS transistor 12 receives the input voltage Vin. An inverter 18 is connected between the gate 16 and a gate 20 of the second NMOS transistor 14. The level shifter 10 includes first and second PMOS transistors 22 and 24 connected in a 35 flip-flop or half latch arrangement. In another configuration, the PMOS transistors 22 and 24 may receive the input voltage Vin and the NMOS transistors 12 and 14 may be connected in the flip-flop or half latch arrangement. In other words, the arrangement of the PMOS transistors 22 and 24 and the 40 NMOS transistors 12 and 14 may be reversed.

Referring now to FIG. 2, a level shifter 30 may include first and second protection NMOS transistors 32 and 34 and first and second protection PMOS transistors 36 and 38. The first and second protection NMOS transistors 32 and 34 communicate with a first protection voltage Vprot1. Conversely, the first and second protection PMOS transistors 36 and 38 communicate with a second protection voltage Vprot2. The protection voltages Vprot1 and Vprot2 bias the protection NMOS transistors 32 and 34 and the protection PMOS transistors 36 and 38, respectively, to protect the level shifter 30 from excessive electric stress.

Referring now to FIGS. 1 and 2, the level shifters 10 and 30 communicate with input supply voltages Vss_in and Vdd_in and output supply voltages Vss_out and Vdd_out. Typically, 55 the input supply voltage Vss_in is equivalent to the output supply voltage Vss_out, and the input supply voltage Vdd_in is not equivalent to the output supply voltage Vdd_out, although those skilled in the art can appreciate that the reverse is true when the positions of the NMOS transistors 12 and 14 60 and the PMOS transistors 22 and 24 are reversed.

The above described relationships between Vss_in and Vss_out and between Vdd_in and Vss_out may limit the operation of the level shifters 10 and 30. For example, in an NMOS driven level shifter, when Vss_out is greater than 65 Vdd_in minus an NMOS threshold voltage Vt, the transistors 12 and 14 remain off regardless of whether a logical 0 or a

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logical 1 is applied to an input node. Consequently, the level shifters 10 and 30 will not function properly. Similarly, in a PMOS driven level shifter, when Vdd_out is less than Vss_in minus a negative PMOS threshold voltage Vt, the transistors 12 and 14 remain off. As a result, when an NMOS driven level shifter is used, an output low level needs to be equivalent to a logic low level (e.g. 0V, or a logical 0). Similarly, when a PMOS driven level shifter is used, an output high level needs to be equivalent to a logic high level (e.g. 3.3V, or a logical 1).

SUMMARY

A level shifter including a level shifter module configured to i) receive an input signal, wherein the input signal varies between a first level and a second level, ii) receive a first voltage supply signal and a second voltage supply signal, and iii) generate a latch control signal based on the input signal and one of the first voltage supply signal and the second voltage supply signal. The level shifter further includes a latch module configured to i) receive the latch control signal, ii) receive the second voltage supply signal and a third voltage supply signal, and iii) generate an output signal based on the latch control signal and one of the second voltage supply signal and the third voltage supply signal.

Further areas of applicability of the present disclosure will become apparent from the detailed description, the claims and the drawings. It should be understood that the detailed description and specific examples are intended for purposes of illustration only and are not intended to limit the scope of the disclosure.

BRIEF DESCRIPTION OF DRAWINGS

The present disclosure will become more fully understood from the detailed description and the accompanying drawings, wherein:

FIG. 1 illustrates a level shifter according to the prior art;

FIG. 2 illustrates a level shifter including protection transistors according to the prior art;

FIG. 3 is a functional block diagram of a level shifter according to the present disclosure;

FIG. 4 illustrates the level shifter according to the present disclosure in further detail;

FIG. 5 illustrates a second level shifter according to the present disclosure;

FIG. 6 illustrates a signal timing diagram of the level shifter according to the present disclosure;

FIG. 7 illustrates a level shifter including multiple latch modules according to the present disclosure;

FIG. 8 illustrates steps of a method for operating a level shifter according to the present disclosure;

FIG. 9A is a functional block diagram of a data storage system including storage units according to the present disclosure;

FIG. 9B is a functional block diagram of a storage unit of the data storage system of FIG. 9A according to the present disclosure;

FIG. 9C is a functional block diagram of a hard disk drive; FIG. 9D is a functional block diagram of a DVD drive;

FIG. 9E is a functional block diagram of a high definition television;

FIG. **9**F is a functional block diagram of a cellular phone; FIG. **9**G is a functional block diagram of a set top box; and FIG. **9**H is a functional block diagram of a mobile device.

DESCRIPTION

The following description is merely exemplary in nature and is in no way intended to limit the disclosure, its applica-

tion, or uses. For purposes of clarity, the same reference numbers will be used in the drawings to identify similar elements. As used herein, the phrase at least one of A, B, and C should be construed to mean a logical (A or B or C), using a non-exclusive logical or. It should be understood that steps within a method may be executed in different order without altering the principles of the present disclosure.

As used herein, the term module may refer to, be part of, or include an Application Specific Integrated Circuit (ASIC), an electronic circuit, a processor (shared, dedicated, or group) 10 and/or memory (shared, dedicated, or group) that execute one or more software or firmware programs, a combinational logic circuit, and/or other suitable components that provide the described functionality.

Typically, when an input to an NMOS level shifter varies between, for example only, 0 and 3.3V, an output of the level shifter may vary between 0 and X, where X is greater than an absolute value of a threshold voltage Vt. In other words, a minimum output low level may not be less than 0. Conversely, when an input to a PMOS level shifter varies between, for 20 example only, 0 and 3.3V, an output of the level shifter may vary between X and 3.3V, where X is less than 3.3V minus a threshold voltage Vt. In other words, a maximum output high level may not be greater than 3.3V.

The level shifter circuit of the present disclosure allows for a broader range of output voltages for the same range of input voltages. For example, when the input to the level shifter varies between 0 and 3.3V, the output may vary between, for example only, X and Y, where X is less than a threshold voltage Vt and Y is greater than X plus the threshold voltage 30 Vt. In other implementations, the output may vary between X and Y, where X is less than 3.3V plus a threshold voltage Vt, and Y is greater than X plus the threshold voltage Vt. Accordingly, neither the minimum nor maximum output levels are limited by the minimum input level of 0V and the maximum input level of 3.3V, respectively. For example, with a 3.3V device, the level shifter may shift anywhere between -3.3V and 3.3V for a total range of 6.6V.

Referring now to FIG. 3, a level shifter 100 according to the present disclosure is shown. The level shifter 100 includes a 40 level shifter module 102 and a latch module 104. The level shifter module 102 receives an input signal 106. For example, the input signal 106 may vary between low and high levels (e.g. between 0 and 3.3V). The level shifter module 102 generates a latch control signal 108 based on the input signal 45 106 and first and second supply signals 110 and 112. For example, when the input signal 106 is high (e.g. 3.3V), the latch control signal 108 is high. When high, the value of the latch control signal 108 may be based on the first supply signal 110. For example only, the first supply signal 110 may 50 be 3.3V (i.e. the same as the high level of the input signal 106).

Conversely, when the input signal 106 is low (e.g. 0V), the latch control signal 108 is low. When low, the value of the latch control signal 108 may be based on the second supply signal 112. The second supply signal 112 may vary between 0V (i.e. the same as the low level of the input signal 106) and -3.3V. Accordingly, the low value of the latch control signal 108 may transition between 0V and -3.3V based on the second supply signal 112.

The latch module 104 generates an output signal 114 based on the latch control signal 108 and a logic input signal 116 The output signal 114 is not limited to a range of 0V to 3.3V. For example, the output signal 114 may transition to a range between -3.3V and 0V

Referring now to FIG. 4, the level shifter module 102 includes first and second PMOS transistors 120 and 122. A

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gate 126 of the first PMOS transistor receives the input signal 106. An inverter 124 is connected between the gate 126 of the first PMOS transistor 120 and a gate 128 of the second PMOS transistor 122. The inverter 124 drives the gate 128 of the second PMOS transistor 122. Each of the PMOS transistors 120 and 122 communicate with the first supply signal 110.

The level shifter module 102 includes first and second NMOS transistors 130 and 132 connected in a flip-flop or half latch arrangement. Each of the transistors 130 and 132 communicate with the second supply signal 112. First and second protection PMOS transistors 134 and 136 and first and second protection NMOS transistors 138 and 140 are connected in a cascade arrangement. Output node 142 generates the latch control signal 108 based on the input signal 106 and the first and second supply signals 110 and 112. For example, the latch control signal 108 may be either high (e.g. 3.3V) or low (e.g. 0 or -3.3V) based on a logic high or low level of the input signal 106.

The latch module **104** includes NMOS transistors **150** and 152. A gate 154 of the NMOS transistor 150 receives the latch control signal 108. Accordingly, the NMOS transistor 150 is on or off based on the latch control signal 108. A gate 156 of the NMOS transistor 152 receives a second latch control signal 157. Accordingly, the NMOS transistor 152 is on or off based on the second latch control signal 157. The NMOS transistor 150 passes an output of a logic gate 158 to a latch 160 that includes inverters 162 and 164 based on the latch control signal 108. Accordingly, the output of the logic gate 158 (e.g. a logical NOR gate) controls an input to the latch 160. The logic gate 158 receives a logic input signal 165 and a data transfer signal 166. A body (i.e. substrate) of each of the NMOS transistors 150 and 152 may be connected to the second supply signal 112 to prevent parasitic PN junctions (not shown).

The inverters 162 and 164 receive the second supply signal 112 and a third supply signal 168 (e.g. at 3.3V). The logic gate 158 may receive the first supply signal 110 as a positive supply signal. Although not shown, each of the logic gate 158 and the inverter 124 may receive a fourth supply signal (such as VSS) 170 as a ground supply signal. For example only, the first supply signal 110 and the fourth supply signal 170 may be equivalent to other logic circuits in an integrated circuit (IC) or system on a chip (SOC) that includes the level shifter 100.

The latch module 104 generates an output signal 172 based on the logic state of the logic input signal 165. For example, the output signal 172 may be based on one of the second supply signal 112 and the third supply signal 168 based on transitions of the logic input signal 165 between low and high states.

Although the second and third supply signals 112 and 168 are given as, for example, 0V and 3.3V, respectively, any voltage can be used as long as the third supply signal 168 is greater than the second supply signal 112 and the latch 160 is functional. For example, the third supply signal 168 may be 0V when the second supply signal 112 is -3.3V. Accordingly, output levels of the level shifter 100 may shift according to the level of the second supply signal 112. In other words, in a high voltage operation mode, the level shifter 100 may shift between 0V and 3.3V. In a low voltage operation mode, the level shifter 100 may shift between -3.3V and 3.3V. Transistors 130 and 132 may receive a protection voltage signal 174.

The level shifter 100 may include a power supply module 200. The power supply module 200 generates the first, second, third, and fourth supply signals 110, 112, 168, and 170, respectively, and the protection voltage signal 174 according to desired operating conditions of the level shifter 100.

Initially, the third supply signal 168 may be equivalent to the first supply signal 110 (e.g. 3.3V) and the fourth supply signal 170 may be equivalent to the second supply signal 112 (e.g. 0V). To pass data from the input logic signal 165 to the latch 160, the input signal 106 is set high (e.g. 3.3V). For example, a high level at the input signal 106 may correspond to a command to write data from the input logic signal 165 to memory (not shown). The data transfer signal 166 is set low (e.g. to logical 0). Accordingly, the output of the logic gate 158 will be controlled according to the input logic signal 165. Further, a polarity of the latch 160 will be set according to the input logic signal 165 passed by the NMOS transistor 150.

When the value of the input logic signal 165 is set in the latch 160, the input signal 106 transitions to a low level, applying the value of the second supply signal 112 and therefore turning off the NMOS transistor 150. The data transfer signal 166 is set high (e.g. to logical 1), transitioning the output of the logic gate 158 to low. For example, since the ground supply signal of the logic gate 158 is the fourth supply signal 170, the low output level of the logic gate 158 may correspond to the fourth supply signal 170 (e.g. ground or 0V).

With the NMOS transistor 150 turned off, the power supply module 200 may change the voltages of the second and third 25 supply signals 112 and 168. For example, the power supply module 200 may change the second and third supply signals 112 and 168 from 0V and 3.3V to -3.3V and 0V, respectively (i.e. shift between a high voltage operation mode to a low voltage operation mode). When the second and third supply 30 signals 112 and 168 are changed, the NMOS transistor 152 is turned on (e.g. via transitioning the second latch control signal 157 to a suitable voltage). When the NMOS transistor 152 is on, the selected output voltage of one of the second and third supply signals 112 and 168 is output as the output signal 35 172. For example, when the input logic signal 165 is high, the output signal 172 is high (e.g. 0V or 3.3V). When the input logic signal 165 is low, the output signal 172 is low (e.g. -3.3V or 0V).

Shifting various input voltages may protect devices in the 40 level shifter such as the NMOS transistors 130, 132, and 150. For example, if the NMOS transistor **150** is a 3.3V device, a gate voltage of 3.3V with a source/drain voltage of -3.3V may cause undue stress on the NMOS transistor 150. Accordingly, the output of the logic gate 158 may be shifted to 0V in 45 this situation to prevent a larger voltage across the NMOS transistor 150. Similarly, the protection voltage signal 174 received at the NMOS transistors 138 and 140 may be changed to the level of the fourth supply signal 170 (e.g. 0V) or ground) when the second supply signal 112 is changed to a 50 lower level such as -3.3V. Accordingly, second and third supply signals 112 and 168 may have any voltage value as long as their difference does not introduce excessive stress on the transistors, their difference is large enough to keep the latch 160 set, and the NMOS transistor 150 remains off during 55 level shifting.

In certain operating conditions of the level shifter 100 shown in FIG. 4, the NMOS transistor 150 may inadvertently be turned on. For example, when the output of the logic gate 158 is 0V and the second supply signal 112 is greater than 0V 60 plus an NMOS threshold voltage Vt, the NMOS transistor 150 may turn on. Similarly, when the output of the logic gate 158 is 0V and the second supply signal 112 is greater than 0V plus a PN diode voltage, a parasitic PN junction diode between a body and a source of the NMOS transistor 150 may 65 turn on. Accordingly, the second supply signal 112 may still be limited.

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Referring now to FIG. 5, a level shifter 200 includes the logic gate 158 and a logic gate 202. The logic gate 202 receives an inverted input logic signal 204 and a logic control signal 206. The logic gate 158 receives an output of the logic gate 202 and the data transfer signal 166. When the second supply signal 112 is less than or equal to 0V (i.e. not positive), the logic control signal 206 is low (i.e. logical 0) and the level shifter 200 operates analogously to the level shifter 100 shown in FIG. 4.

When the second supply signal 112 is greater than 0V (i.e. positive), the logic control signal 206 is high (i.e. logical 1) and the data transfer signal 166 is low (i.e. logical 0). Accordingly, in this circumstance, the output of the logic gate 158 is forced high (i.e. to 3.3V), thereby ensuring that the NMOS transistor 150 remains off even when the second supply signal 112 is positive. In other words, the output of the logic gate 158 as shown in FIG. 5 may be low (e.g. 0V) or high (e.g. 3.3V) based on whether the second supply signal 112 is negative or positive.

Referring now to FIG. 6, a timing diagram 300 for the various signals described in FIGS. 3-5 is shown. The output signal 172 follows one of the input logic signal 165 and the inverted input logic signal 204 for FIGS. 4 and 5, respectively. When the input signal 106 is high, none of the values of the supply signals are changed and the value of the input logic signal 165 (or the inverted input logic signal 204) is set in the latch 160. When the input signal 106 is low, the latch control signal 108 transitions low to turn off the NMOS transistor 150 as indicated at 302. At 304, the data transfer signal 166 transitions low to ensure that the NMOS transistor 150 remains off during level shifting.

At 306, the second supply signal 112 is shifted from 0V to -3.3V. The third supply signal 168 is shifted from 3.3V to 0V. The protection voltage signal 174 may be shifted from 3.3V to 0V to reduce stress on certain devices. The first supply signal 110 and the fourth supply signal 170 remain high (e.g. 3.3V) and low (e.g. ground or 0V), respectively.

Referring now to FIG. 7, a level shifter module 400 may provide a latch control signal 402 to multiple latch modules 404-1, 404-2, 404-3, . . . , and 404-N (referred to collectively as latch modules 404). Each of the latch modules 404 may generate a different output signal 406 based on respective input signals 408. The latch modules 404 may input data based on the output signals 406 according to the level shifting operation as described in FIGS. 3-6. For example, each of the latch modules 404 may input data to an input line of memory 410 (which may include, for example only, a memory IC). Alternatively, a single one of the latch modules 404 may be implemented with multiplexing to input data to multiple lines of the memory 410. For example only, the memory 410 may include nonvolatile memory.

Referring now to FIG. 8, a method 500 for operating a level shifter having a level shifter module 102 and a latch module 104 according to the present disclosure begins in step 502. In step 504, data is input to the latch module 104 with supply voltages at a first level. In step 506, an input signal to the level shifter module 102 transitions low. In step 508, a data transfer signal input to the latch module 104 transitions low to set the data in the latch module 104. In step 510, levels of supply signals to the level shifter module 102 and the latch module 104 are shifted between high and low operation voltages. In step 512, the data is output from the latch module 104 according to the new operation voltages. The method 500 ends in step 514.

Referring now to FIGS. 9A-9H, various exemplary implementations incorporating the teachings of the present disclosure are shown.

Referring now to FIGS. 9A and 9B, the teachings of the present disclosure can be extended to storage products including data storage systems and solid-state disks. The architecture and configuration of the data storage system shown in FIGS. 9A and 9B are exemplary. Other architectures 5 and device configurations are contemplated.

In FIG. 9A, for example only, a data storage system 520 may comprise a storage area network (SAN) control module 522, a SAN switching unit 524, and storage units 526-1, **526-2**, . . . , and **526-***n* (collectively storage units **526**). The 10 SAN control module 522 may comprise a control unit that interfaces the data storage system **520** to one or more external devices (not shown) through an input/output (I/O) bus 528. For example, the control unit may include a processor, a microprocessor, an ASIC, a state machine, etc. For example, 15 the external devices may include a host, a server, etc. The I/O bus 528 may comprise a bus that provides high speed and wide bandwidth for data transmission. For example, the I/O bus **528** may include fiber-channels, Ethernet, etc. For example only, the transmission speed of the I/O bus **528** may 20 be faster than 10 gigabits per second (10 Gb/s).

Additionally, the SAN control module 522 may control the SAN switching unit **524**. For example only, the SAN switching unit **524** may include a plurality of switches. Each of the switches may interface with one of the storage units **526** and 25 may be controlled via control signals from the SAN control module **522**. The storage units **526** may store information that includes audio data, video data, and/or any other types of data in a digital format.

In FIG. 9B, for example only, one of the storage units **526** 30 (e.g., the storage unit 526-n) may comprise a storage unit control module **530**, solid-state drives (SSDs) **532-1**,..., and 532-n (collectively SSDs 532), a startup storage unit 534, and a bus 536. An SSD may refer to a data storage device that uses solid-state memory to store data, such as a flash memory 35 drive. Each of the SSDs 532 may comprise one or more of the memory 410 of FIG. 7, shown as memory ICs 410a11-**410***nxy*. The variables a and n refer to the SSD. The variables x and y refer to a memory IC within a SSD. The variable a may be equal to 1 and the variables n, x, and y may be integers 40 greater than 1. Additionally, each of the SSDs 532 may comprise a memory controller (not shown) that controls the one or more of the memory ICs 410a11-410nxy. The startup storage unit 534 may include code for operating the storage unit control module **530**. Using the code, the storage unit control 45 module 530 may control the SSDs 532 via the bus 536.

Referring now to FIG. 9C, the teachings of the disclosure can be implemented in memory 612 of a hard disk drive (HDD) 600. The HDD 600 includes a hard disk assembly (HDA) 601 and an HDD printed circuit board (PCB) 602. The 50 HDA 601 may include a magnetic medium 603, such as one or more platters that store data, and a read/write device 604. The read/write device **604** may be arranged on an actuator arm 605 and may read and write data on the magnetic medium 603. Additionally, the HDA 601 includes a spindle motor 606 55 that rotates the magnetic medium 603 and a voice-coil motor (VCM) 607 that actuates the actuator arm 605. A preamplifier device 608 amplifies signals generated by the read/write device 604 during read operations and provides signals to the read/write device 604 during write operations.

The HDD PCB **602** includes a read/write channel module (hereinafter, "read channel") 609, a hard disk controller (HDC) module 610, a buffer 611, memory 612, a processor 613, and a spindle/VCM driver module 614. The read channel preamplifier device 608. The HDC module 610 controls components of the HDA 601 and communicates with an external

device (not shown) via an I/O interface 615. The external device may include a computer, a multimedia device, a mobile computing device, etc. The I/O interface 615 may include wireline and/or wireless communication links.

The HDC module 610 may receive data from the HDA 601, the read channel 609, the buffer 611, memory 612, the processor 613, the spindle/VCM driver module 614, and/or the I/O interface 615. The processor 613 may process the data, including encoding, decoding, filtering, and/or formatting. The processed data may be output to the HDA 601, the read channel 609, the buffer 611, nonvolatile memory 612, the processor 613, the spindle/VCM driver module 614, and/or the I/O interface 615.

The HDC module 610 may use the buffer 611 and/or nonvolatile memory **612** to store data related to the control and operation of the HDD 600. The buffer 611 may include DRAM, SDRAM, etc. Memory 612 may include RAM or any suitable type of semiconductor or solid-state memory, such as flash memory (including NAND and NOR flash memory), phase change memory, magnetic RAM, and multi-state memory, in which each memory cell has more than two states. The spindle/VCM driver module 614 controls the spindle motor 606 and the VCM 607. The HDD PCB 602 includes a power supply 616 that provides power to the components of the HDD **600**.

Referring now to FIG. 9D, the teachings of the disclosure can be implemented in memory 623 of a DVD drive 618 or of a CD drive (not shown). The DVD drive **618** includes a DVD PCB 619 and a DVD assembly (DVDA) 620. The DVD PCB 619 includes a DVD control module 621, a buffer 622, memory 623, a processor 624, a spindle/FM (feed motor) driver module 625, an analog front-end module 626, a write strategy module 627, and a DSP module 628.

The DVD control module **621** controls components of the DVDA 620 and communicates with an external device (not shown) via an I/O interface 629. The external device may include a computer, a multimedia device, a mobile computing device, etc. The I/O interface 629 may include wireline and/or wireless communication links.

The DVD control module **621** may receive data from the buffer 622, memory 623, the processor 624, the spindle/FM driver module 625, the analog front-end module 626, the write strategy module 627, the DSP module 628, and/or the I/O interface 629. The processor 624 may process the data, including encoding, decoding, filtering, and/or formatting. The DSP module 628 performs signal processing, such as video and/or audio coding/decoding. The processed data may be output to the buffer 622, memory 623, the processor 624, the spindle/FM driver module 625, the analog front-end module 626, the write strategy module 627, the DSP module 628, and/or the I/O interface **629**.

The DVD control module 621 may use the buffer 622 and/or memory 623 to store data related to the control and operation of the DVD drive 618. The buffer 622 may include DRAM, SDRAM, etc. Memory 623 may include RAM or any suitable type of semiconductor or solid-state memory, such as flash memory (including NAND and NOR flash memory), phase change memory, magnetic RAM, and multi-state memory, in which each memory cell has more than two states. The DVD PCB **619** includes a power supply **630** that provides power to the components of the DVD drive 618.

The DVDA 620 may include a preamplifier device 631, a laser driver 632, and an optical device 633, which may be an optical read/write (ORW) device or an optical read-only (OR) 609 processes data received from and transmitted to the 65 device. A spindle motor 634 rotates an optical storage medium 635, and a feed motor 636 actuates the optical device 633 relative to the optical storage medium 635.

When reading data from the optical storage medium 635, the laser driver provides a read power to the optical device 633. The optical device 633 detects data from the optical storage medium 635, and transmits the data to the preamplifier device 631. The analog front-end module 626 receives 5 data from the preamplifier device 631 and performs such functions as filtering and A/D conversion. To write to the optical storage medium 635, the write strategy module 627 transmits power level and timing data to the laser driver 632. The laser driver 632 controls the optical device 633 to write 10 data to the optical storage medium 635.

Referring now to FIG. 9E, the teachings of the disclosure can be implemented in memory 641 of a high definition television (HDTV) 637. The HDTV 637 includes an HDTV control module 638, a display 639, a power supply 640, 15 memory 641, a storage device 642, a network interface 643, and an external interface 645. If the network interface 643 includes a wireless local area network interface, an antenna (not shown) may be included.

The HDTV 637 can receive input signals from the network 20 interface 643 and/or the external interface 645, which can send and receive data via cable, broadband Internet, and/or satellite. The HDTV control module 638 may process the input signals, including encoding, decoding, filtering, and/or formatting, and generate output signals. The output signals 25 may be communicated to one or more of the display 639, memory 641, the storage device 642, the network interface 643, and the external interface 645.

Memory 641 may include random access memory (RAM) and/or nonvolatile memory. Nonvolatile memory may 30 include any suitable type of semiconductor or solid-state memory, such as flash memory (including NAND and NOR flash memory), phase change memory, magnetic RAM, and multi-state memory, in which each memory cell has more than two states. The storage device 642 may include an optical storage drive, such as a DVD drive, and/or a hard disk drive (HDD). The HDTV control module 638 communicates externally via the network interface 643 and/or the external interface 645. The power supply 640 provides power to the components of the HDTV 637.

Referring now to FIG. 9F, the teachings of the disclosure can be implemented in memory 664 of a cellular phone 658. The cellular phone 658 includes a phone control module 660, a power supply 662, memory 664, a storage device 666, and a cellular network interface 667. The cellular phone 658 may 45 include a network interface 668, a microphone 670, an audio output 672 such as a speaker and/or output jack, a display 674, and a user input device 676 such as a keypad and/or pointing device. If the network interface 668 includes a wireless local area network interface, an antenna (not shown) may be 50 included.

The phone control module 660 may receive input signals from the cellular network interface 667, the network interface 668, the microphone 670, and/or the user input device 676. The phone control module 660 may process signals, including encoding, decoding, filtering, and/or formatting, and generate output signals. The output signals may be communicated to one or more of memory 664, the storage device 666, the cellular network interface 667, the network interface 668, and the audio output 672.

Memory **664** may include random access memory (RAM) and/or nonvolatile memory. Nonvolatile memory may include any suitable type of semiconductor or solid-state memory, such as flash memory (including NAND and NOR flash memory), phase change memory, magnetic RAM, and 65 multi-state memory, in which each memory cell has more than two states. The storage device **666** may include an opti-

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cal storage drive, such as a DVD drive, and/or a hard disk drive (HDD). The power supply 662 provides power to the components of the cellular phone 658.

Referring now to FIG. 9G, the teachings of the disclosure can be implemented in memory 683 of a set top box 678. The set top box 678 includes a set top control module 680, a display 681, a power supply 682, memory 683, a storage device 684, and a network interface 685. If the network interface 685 includes a wireless local area network interface, an antenna (not shown) may be included.

The set top control module **680** may receive input signals from the network interface **685** and an external interface **687**, which can send and receive data via cable, broadband Internet, and/or satellite. The set top control module **680** may process signals, including encoding, decoding, filtering, and/or formatting, and generate output signals. The output signals may include audio and/or video signals in standard and/or high definition formats. The output signals may be communicated to the network interface **685** and/or to the display **681**. The display **681** may include a television, a projector, and/or a monitor.

The power supply **682** provides power to the components of the set top box **678**. Memory **683** may include random access memory (RAM) and/or nonvolatile memory. Nonvolatile memory may include any suitable type of semiconductor or solid-state memory, such as flash memory (including NAND and NOR flash memory), phase change memory, magnetic RAM, and multi-state memory, in which each memory cell has more than two states. The storage device **684** may include an optical storage drive, such as a DVD drive, and/or a hard disk drive (HDD).

Referring now to FIG. 9H, the teachings of the disclosure can be implemented in memory 692 of a mobile device 689. The mobile device 689 may include a mobile device control module 690, a power supply 691, memory 692, a storage device 693, a network interface 694, and an external interface 699. If the network interface 694 includes a wireless local area network interface, an antenna (not shown) may be included.

The mobile device control module 690 may receive input signals from the network interface 694 and/or the external interface 699. The external interface 699 may include USB, infrared, and/or Ethernet. The input signals may include compressed audio and/or video, and may be compliant with the MP3 format. Additionally, the mobile device control module 690 may receive input from a user input 696 such as a keypad, touchpad, or individual buttons. The mobile device control module 690 may process input signals, including encoding, decoding, filtering, and/or formatting, and generate output signals.

The mobile device control module **690** may output audio signals to an audio output **697** and video signals to a display **698**. The audio output **697** may include a speaker and/or an output jack. The display **698** may present a graphical user interface, which may include menus, icons, etc. The power supply **691** provides power to the components of the mobile device **689**. Memory **692** may include random access memory (RAM) and/or nonvolatile memory.

Nonvolatile memory may include any suitable type of semiconductor or solid-state memory, such as flash memory (including NAND and NOR flash memory), phase change memory, magnetic RAM, and multi-state memory, in which each memory cell has more than two states. The storage device **693** may include an optical storage drive, such as a DVD drive, and/or a hard disk drive (HDD). The mobile

device may include a personal digital assistant, a media player, a laptop computer, a gaming console, or other mobile computing device.

Those skilled in the art can now appreciate from the foregoing description that the broad teachings of the disclosure 5 can be implemented in a variety of forms. Therefore, while this disclosure includes particular examples, the true scope of the disclosure should not be so limited since other modifications will become apparent upon a study of the drawings, the specification, and the following claims.

What is claimed is:

- 1. A level shifter, comprising:
- a level shifter module configured to i) receive an input signal, wherein the input signal varies between a first level and a second level, ii) receive a first voltage supply 15 signal and a second voltage supply signal, and iii) generate a latch control signal based on the input signal and one of the first voltage supply signal and the second voltage supply signal, wherein
 - when the input signal is at the first level, the latch control signal is based on the input signal and the first voltage supply signal, and
 - when the input signal is at the second level, the latch control signal is based on the input signal and the second voltage supply signal; and
- a latch module configured to i) receive the latch control signal, ii) receive the second voltage supply signal and a third voltage supply signal, and iii) generate an output signal based on the latch control signal and one of the second voltage supply signal and the third voltage supply signal, wherein
 - in a first mode, the second voltage supply signal has a first voltage and the third voltage supply signal has a second voltage, and
 - in a second mode, the second voltage supply signal has a third voltage and the third voltage supply signal has a fourth voltage,
 - wherein the second voltage is greater than the first voltage, and the fourth voltage is greater than the third voltage.
- 2. The level shifter of claim 1, wherein the third voltage is greater than the first voltage, and the fourth voltage is greater than the second voltage.
- 3. The level shifter of claim 1, wherein in the first mode i) the first voltage supply signal has the second voltage equivalent to the third voltage supply signal, and ii) the second voltage is greater than the first voltage.
- 4. The level shifter of claim 1, wherein in the second mode i) the first voltage supply signal has the second voltage, ii) the second voltage is greater than the fourth voltage associated 50 with the third voltage supply signal, and iii) the fourth voltage is greater than the third voltage associated with the second voltage supply signal.
- 5. The level shifter of claim 1, wherein the first voltage is equal to the fourth voltage.
- 6. The level shifter of claim 1, further comprising a power supply module that selects between the first mode and the second mode based on the input signal.
- 7. The level shifter of claim 1, wherein the output signal is further based on an input logic signal that varies between a 60 first logic state and a second logic state.

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- 8. The level shifter of claim 7, wherein the output signal is based on i) the second voltage supply signal when the input logic signal has the first logic state and ii) the third voltage supply signal when the input logic signal has the second logic state.
- 9. A method of operating a level shifter, the method comprising:

using a level shifter,

- receiving an input signal, wherein the input signal varies between a first level and a second level,
- generating a latch control signal based on the input signal and one of a first voltage supply signal and a second voltage supply signal, wherein
 - when the input signal is at the first level, the latch control signal is based on the input signal and the first voltage supply signal, and
 - when the input signal is at the second level, the latch control signal is based on the input signal and the second voltage supply signal; and
- generating an output signal based on the latch control signal and one of the second voltage supply signal and a third voltage supply signal, wherein
 - in a first mode, the second voltage supply signal has a first voltage and the third voltage supply signal has a second voltage, and
 - in a second mode, the second voltage supply signal has a third voltage and the third voltage supply signal has a fourth voltage,
 - wherein the second voltage is greater than the first voltage, and the fourth voltage is greater than the third voltage.
- 10. The method of claim 9, wherein the third voltage is greater than the first voltage, and the fourth voltage is greater than the second voltage.
- 11. The method of claim 9, wherein in the first mode i) the first voltage supply signal has the second voltage equivalent to the third voltage supply signal, and ii) the second voltage is greater than the first voltage.
- 12. The method of claim 9, wherein in the second mode i) the first voltage supply signal has the second voltage, ii) the second voltage is greater than the fourth voltage associated with the third voltage supply signal, and iii) the fourth voltage is greater than the third voltage associated with the second voltage supply signal.
- 13. The method of claim 9, wherein the first voltage is equal to the fourth voltage.
- 14. The method of claim 9, further comprising selecting between the first mode and the second mode based on the input signal.
- 15. The method of claim 9, wherein the output signal is further based on an input logic signal that varies between a first logic state and a second logic state.
- 16. The method of claim 15, wherein the output signal is based on i) the second voltage supply signal when the input logic signal has the first logic state and ii) the third voltage supply signal when the input logic signal has the second logic state.

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